

Final 2024 PDC Slate for 74th ECTC



| AM Courses | PM Courses |
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| PDC #1: High Reliability Soldering in Semiconductor Packaging – Ning-Cheng Lee (ShinePure Hi-Tech) | PDC #9: Additive Flexible Hybrid Electronics – Manufacturing and Reliability – Pradeep Lall (Auburn University) |
| PDC #2: Photonic Technologies for Communication, Sensing, and Displays --Torsten Wipiejewski (Huawei Technologies) | PDC #10: Fundamentals of RF Design and Fabrication Processes of Fan-Out Wafer/Panel Level and Advanced RF Packages – Ivan Ndip (Fraunhofer IZM/Brandenburg University of Technology) & Markus Wohrmann (Fraunhofer IZM) |
| PDC #3: From Wafer to Panel Level Packaging - Tanja Braun and Piotr Mackowiak (Fraunhofer IZM) | PDC #11: Advanced Packaging – Fan-Out, Chiplet, and Heterogeneous Integration – John Lau (Unimicron) |
| PDC #4: Eliminating Failure Mechanisms in Advanced Packages – Darwin Edwards (Edwards Enterprises) | PDC #12: Analysis of Fracture and Delamination in Microelectronic Packages – Andrew Tay |
| PDC #5: Navigating Thermal and Reliability Challenges in Chip Components for Automotive High-Performance Compute Systems – Fen Chen (Automotive Reliability/Validation Consultation Services) | PDC #13: Advanced Packaging for MEMS and Sensors – Horst Theuss |
| PDC #6: Polymers for Advanced Packaging - Jeffrey Gotro (InnoCentrix) | PDC #14: Nano Materials and Polymer Composites for Electronic Packaging -- Prof. C. P. Wong (Georgia Tech) & Daniel Lu (Henkel Corporation) |
| PDC #7: Flip Chip Technologies – Shengmin Wen (HaiSemi, Inc) | PDC #15: Design-on-Simulation for Advanced Packaging Reliability and Life Prediction - Kuo-Ning Chiang (National Tsing Hua University) & Xuejun Fan(Lamar University) |
| PDC #8: Reliable Integrated Thermal Packaging for Power Electronics – Patrick McCluskey (University of Maryland) | PDC #16: Thermal Spreading and Contact Resistance - Yuri Muzychka (Memorial University of Newfoundland) & Marc Hodes (Tufts University) |